



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hawks, et al.

Serial No.: 09/638,172

Filed: August 11, 2000

For: **Method and Structure for Securing a
Mold Compound to a Printed Circuit
Board**

Art Unit: 2831

Examiner: Hung V. Ngo

#6/B
Hawkins
1/16/02

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AMENDMENT AND RESPONSE TO OFFICE ACTION

Honorable Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Dear Sir/Madam:

This is in response to the Office Action dated August 1, 2001 in the above-referenced patent application. Please enter and consider the following amendments and remarks.

In the Claims:

Marked up version of once amended claim 11:

11. (Once Amended) A structure comprising:

a printed circuit board including a die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of
said printed circuit board;

17 { said printed circuit board further comprising a second layer of metal on said top
surface of said printed circuit board, wherein said second layer of metal is situated below
said die;

12 { a through hole traversing said first and second layers of metal of [in] said printed
circuit board, said through hole being adjacent to said die, said through hole being filled
with a mold compound, said mold compound surrounding and covering said die, wherein
said mold compound is locked into said first and second layers of metal of said printed
circuit board.

Clean version of once amended claim 11:

11. A structure comprising:

13 { a printed circuit board including a die attached to a top surface of said printed
circuit board;

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cancel

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said die, said through hole being filled with a mold compound, said mold compound surrounding and covering said die, wherein said mold compound is locked into said first and second layers of metal of said printed circuit board.

✓ Please cancel claims 12-13 and 17.

Marked up version of once amended claim 18:

18. (Once Amended) The structure of claim [17] 11 further comprising a layer of die attach between said die and said [first] second layer of metal.

Clean version of once amended claim 18:

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18. The structure of claim 11 further comprising a layer of die attach between said die and said second layer of metal.

Marked up version of once amended claim 19:

19. (Once Amended) The structure of claim [17] 11 wherein said [first] second layer of metal comprises gold-plated copper.

Clean version of once amended claim 19:

B³ 19. The structure of claim 11 wherein said second layer of metal comprises gold-plated copper.